

REMARKS

Claims 1-77 are pending, of which claims 28-48 have been withdrawn as being directed to a non-elected invention. Accordingly, claims 1-27 and 49-77 have been examined in the current Office Action.

I. Preliminary Matters

The Examiner has not acknowledged the drawings filed on August 21, 2003. Accordingly, Applicant respectfully requests the Examiner to indicate, in the next Office Action, whether the drawings are acceptable.

Also, the Examiner has not acknowledged Applicant's claim for foreign priority. Accordingly, Applicant respectfully requests the Examiner to mark, in the next Office Action, the appropriate boxes under item #12 of the Office Action Summary.

II. Rejections under 35 U.S.C. § 103(a)

The Examiner has rejected claims 1-3, 6, 26, 59, 60 and 62-67 under 35 U.S.C. § 103(a) as allegedly being unpatentable over U.S. Patent No. 6,376,769 to Chung ("Chung").

A. Claim 1

Applicant submits that claim 1 is patentable over the cited reference. For example, claim 1 recites that, "at least a first portion between a surface of said semiconductor element facing said solder bumps and said flexible substrate is not fixed." (emphasis added)

In view of the above recitation, thermal stress caused by expansion/contraction movement of the motherboard can be avoided by making the flexible interposer substrate expand

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and contract in sync with the expansion/contraction movement of the motherboard through the solder bumps when the motherboard alternates between thermal expansion and cold shrinkage following temperature change (see, non-limiting embodiments on pg. 31, lines 10-14 and pg. 33, lines 3-11).

On the other hand, the Chung reference does not teach or suggest the feature recited above. Rather, according to Chung's Fig. 20, which is cited by the Examiner on page 2 of the Office Action, an electronic device 420 and the flexible interposer 410 are fixed to each other by the solder balls. In addition, Chung does not provide any discussion or suggestion regarding the thermal stress caused by expansion/contraction movement of a motherboard. Thus, Chung does not teach or suggest the features recited in claim 1.

For the foregoing reasons, Applicant submits that claim 1 is patentable over the cited reference, and respectfully requests the Examiner to reconsider and withdraw the rejection.

Further, since claims 2, 3, 6, 26, 59, 60 and 62-67 are dependent upon claim 1, Applicant submits that such claims are patentable at least by virtue of their dependency.

Applicant notes that the Examiner has omitted to reject claim 24 in view of Chung. However, since claim 24 is dependent upon claim 1, Applicant submits that such claim is patentable at least by virtue of its dependency.

III. Allowable Subject Matter

The Examiner has indicated that claims 11-23, 25, 27, 49-58, 68 and 70-77 are allowed, and claims 4, 5, 7-10 and 61 contain allowable subject matter, but are objected to as being dependent upon a rejected base claim.

The Examiner has not provided any comments regarding claim 69. However, since claim 69 is dependent upon allowed claims 11 and 13, Applicant submits that claim 69 is allowable at least by virtue of its dependency.

Further, on page 4 of the Office Action, the Examiner provides reasons why the claims are considered to be allowable. However, Applicant submits that independent reasons, other than those cited by the Examiner, exist for the allowability of the claims.

IV. Conclusion

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

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